

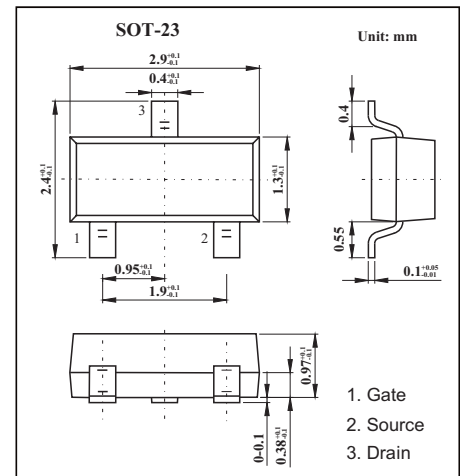
SOT-23 Plastic-Encapsulate MOSFETS

Features

- VDS (V) = -20V
- ID = -3 A
- RDS(ON) < 97mΩ (VGS = -4.5V)
- RDS(ON) < 130mΩ (VGS = -2.5V)
- RDS(ON) < 190mΩ (VGS = -1.8V)
- P-Channel Enhancement Mode Field Effect Transistor

MECHANICAL DATA

- Case style:SOT-23molded plastic
- Mounting position:any



MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	±8	V
Continuous Drain Current *1	I _D	T _A =25°C	-3
		T _A =70°C	-2.4
Pulsed Drain Current *2	I _{DM}	-15	A
Power Dissipation *1	P _D	T _A =25°C	1.4
		T _A =70°C	0.9
Thermal Resistance.Junction-to-Ambient *1	R _{θJA}	125	°C/W
Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 150	°C

*1The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz.

Copper, in a still air environment with T_A =25°C

*2 Repetitive rating, pulse width limited by junction temperature.

MOSFET ELECTRICAL CHARACTERISTICS $T_a=25\text{ }^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{DS}	$I_D=-250\text{ }\mu\text{ A}$, $V_{GS}=0\text{ V}$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-16\text{ V}$, $V_{GS}=0\text{ V}$			-1	$\mu\text{ A}$
		$V_{DS}=-16\text{ V}$, $V_{GS}=0\text{ V}$, $T_J=55\text{ }^{\circ}\text{C}$			-5	
Gate-Body leakage current	I_{GSS}	$V_{DS}=0\text{ V}$, $V_{GS}=\pm 8\text{ V}$			± 100	$\mu\text{ A}$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=-250\text{ }\mu\text{ A}$	-0.3	-0.55	-1	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-4.5\text{ V}$, $I_D=-3\text{ A}$		81	97	m Ω
		$V_{GS}=-4.5\text{ V}$, $I_D=-3\text{ A}$ $T_J=125\text{ }^{\circ}\text{C}$		111	135	
		$V_{GS}=-2.5\text{ V}$, $I_D=-2.6\text{ A}$		108	130	
		$V_{GS}=-1.8\text{ V}$, $I_D=-1\text{ A}$		146	190	
On state drain current	$I_{D(on)}$	$V_{GS}=-4.5\text{ V}$, $V_{DS}=-5\text{ V}$	-15			A
Forward Transconductance	g_{FS}	$V_{DS}=-5\text{ V}$, $I_D=-3\text{ A}$	4	7		S
Input Capacitance	C_{iss}	$V_{GS}=0\text{ V}$, $V_{DS}=-10\text{ V}$, $f=1\text{ MHz}$		540		pF
Output Capacitance	C_{oss}			72		pF
Reverse Transfer Capacitance	C_{rss}			49		pF
Gate resistance	R_g	$V_{GS}=0\text{ V}$, $V_{DS}=0\text{ V}$, $f=1\text{ MHz}$		12		Ω
Total Gate Charge	Q_g	$V_{GS}=-4.5\text{ V}$, $V_{DS}=-10\text{ V}$, $I_D=-3\text{ A}$		6.1		nC
Gate Source Charge	Q_{gs}			0.6		nC
Gate Drain Charge	Q_{gd}			1.6		nC
Turn-On DelayTime	$t_{D(on)}$				10	
Turn-On Rise Time	t_r	$V_{GS}=-4.5\text{ V}$, $V_{DS}=-10\text{ V}$, $R_L=3.3\text{ }\Omega$, $R_{GEN}=3\text{ }\Omega$		12		ns
Turn-Off DelayTime	$t_{D(off)}$			44		ns
Turn-Off Fall Time	t_f			22		ns
Body Diode Reverse Recovery Time	t_{rr}	$I_F=-3\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$		21		ns
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F=-3\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$		7.5		nC
Maximum Body-Diode Continuous Current	I_S				-2	A
Diode Forward Voltage	V_{SD}	$I_S=-1\text{ A}$, $V_{GS}=0\text{ V}$		-0.78	-1	V